

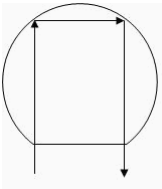
Part Number

Customer

Category	Parameter	Specification	Measurement Method
OverallWafer	1.0 Diameter	150.00 +/- 0.50 mm	
	2.0 Primary Flat Orientation	{110} +/- 1.0 degree	Wafer Vendor
	3.0 Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0 Secondary Flat Orientation	None	Wafer Vendor
	5.0 Overall Thickness	730.00 +/- 17.00 μ m	ADE, 100%
	6.0 Total Thickness Variation (TTV)	<5.00 μ m	Guaranteed by Process
	7.0 Bow	<60.00 μ m	ADE to ASTM F534, 20%
	8.0 Warp	<60.00 μ m	ADE to ASTM F657, 20%
	9.0 Edge Chips	0	Bright Light, 100%
	10.0 Edge Exclusion	5mm	
HandleSilicon	11.0 Handle Growth Method	CZ	Wafer Vendor
	12.0 Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	13.0 Handle Thickness	500.00 +/- 15.00 μ m	ADE, 100%
	14.0 Handle Doping Type	P	Wafer Vendor
	15.0 Handle Dopant	Boron	Wafer Vendor
	16.0 Handle Resistivity	0.001 - 0.01 Ohmcm	Wafer Vendor
	17.0 Backside Finish	Polished with laser marking	Guaranteed by process
BuriedOxide	18.0 Oxide Type	NONE	Guaranteed by process
DeviceSilicon	19.0 Device Growth Method	FZ	Wafer Vendor
	20.0 Device Orientation	{100} +/- 1 degree	Wafer Vendor
	21.0 Nominal Thickness	230.00 +/- 2.00 μ m	Single Point, 100%
	22.0 Distance to device silicon edge from wafer edge	<= 2.0mm	Typical by process
	23.0 Edge Removal Depth in Handle	<100um	Guaranteed by process
	24.0 Device Doping Type	P	Wafer Vendor
	25.0 Device Dopant	Boron	Wafer Vendor
	26.0 Device Resistivity	5000 - 12000 Ohmcm	Wafer Vendor
	27.0 Voids	0	Bright Light, 100% (note 2)
	28.0 Scratches	0	Bright Light, 100% (note 2)
	29.0 Haze	none	Bright Light, 100% (note 2)

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Category	Parameter	Specification	Measurement Method
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Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	

Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		
	2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.		
	3. 9 point measurement are as shown in the diagram below:		



Additional Information